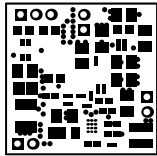
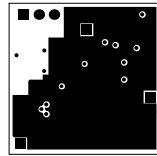


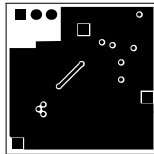
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Top Overlay	GENERATED : 10/10/2013 4:54:40 PM	TEXAS INSTRUMENTS	



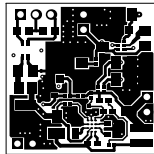
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Top Solder Mask	GENERATED : 10/10/2013 4:54:41 PM	TEXAS INSTRUMENTS	



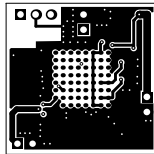
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Midlayer 1	GENERATED : 10/10/2013 4:54:41 PM	TEXAS INSTRUMENTS	



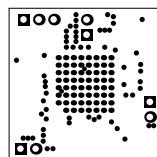
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Midlayer 2	GENERATED : 10/10/2013 4:54:41 PM	TEXAS INSTRUMENTS	



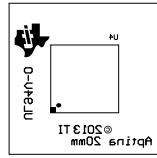
	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Top Layer	GENERATED : 10/10/2013 4:54:42 PM	TEXAS INSTRUMENTS	



	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Bottom Layer	GENERATED : 10/10/2013 4:54:42 PM	TEXAS INSTRUMENTS	

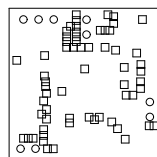


	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Bottom Solder Mask	GENERATED : 10/10/2013 4:54:43 PM	TEXAS INSTRUMENTS	



	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Bottom Overlay	GENERATED : 10/10/2013 4:54:43 PM	TEXAS INSTRUMENTS	

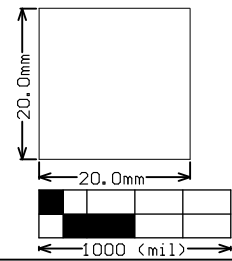




Symbol	Hit Count	Tool Size	Plated	Hole Type
□	62	10mil (0.254mm)	PTH	Round
○	9	35mil (0.889mm)	PTH	Round
	71 Total			

Drill Table

	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Drill Drawing	GENERATED : 10/10/2013 4:54:44 PM		TEXAS INSTRUMENTS



	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
Board Dimensions	GENERATED : 10/10/2013 4:54:44 PM		TEXAS INSTRUMENTS

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